



LP-150-LDS

is a glass fiber and mineral filled PPS compound suitable for LPKF Laser Direct Structuring (LDS) process.

Color: Black

Properties of LP-150-LDS			
Properties	Test Method	Unit	LP-150-LDS
General Information			GF/Filler
Physical			
Density Water absorption, 23°C /24hrs. Mold shrinkage ^a	ISO 1183 ISO 62 ISO 294-4	g/cm³ % %	1.81 0.02 0.3 / 1.0
Mechanical			
Tensile strength Tensile modulus Tensile strain at break Flexural strength Flexural modulus Flexural strain at break Charpy impact strength notched unnotched Co-eff. of friction ^b , static / dynamic	ISO 527-1, -2 ISO 527-1, -2 ISO 527-1, -2 ISO 178 ISO 178 ISO 178 ISO 179/1eA ISO 179/1eU	MPa GPa % MPa GPa % kJ/m ² kJ/m ²	120 11.3 1.3 170 11.3 1.6 3 19 -/-
Thermal			
Heat deflection temperature, 1.80 MPa Co-eff. of linear thermal expansion ^a , -50~50°C Co-eff. of linear thermal expansion ^a , 100~200°C Flammability ^c / thickness (mm)	ISO 75-1, -2 ISO 11359-1 ISO 11359-1 UL-94	°C x 10⁻⁵/K x 10⁻⁵/K -	> 265 1.9 / 4.0 1.9 / 10.3 V-0 / 0.75
Electrical			
Dielectric strength, t=1.0mm Dielectric constant, 1MHz Dissipation factor, 1MHz Comparative tracking index (CTI) Volume resistivity	IEC 60243-1 IEC 60250 IEC 60250 IEC 60112 IEC 60093	kV/mm - - V Ω.cm	20 4 0.006 - 10 ¹⁶
Process Conditions			
Cylinder temperature Mold temperature	-	°C °C	290-320 130-150

a: Flow direction / Transverse direction, b: P=150kPa, V=0.3m/s, PPS vs. carbon steel

c: Internal test result at DIC lab

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